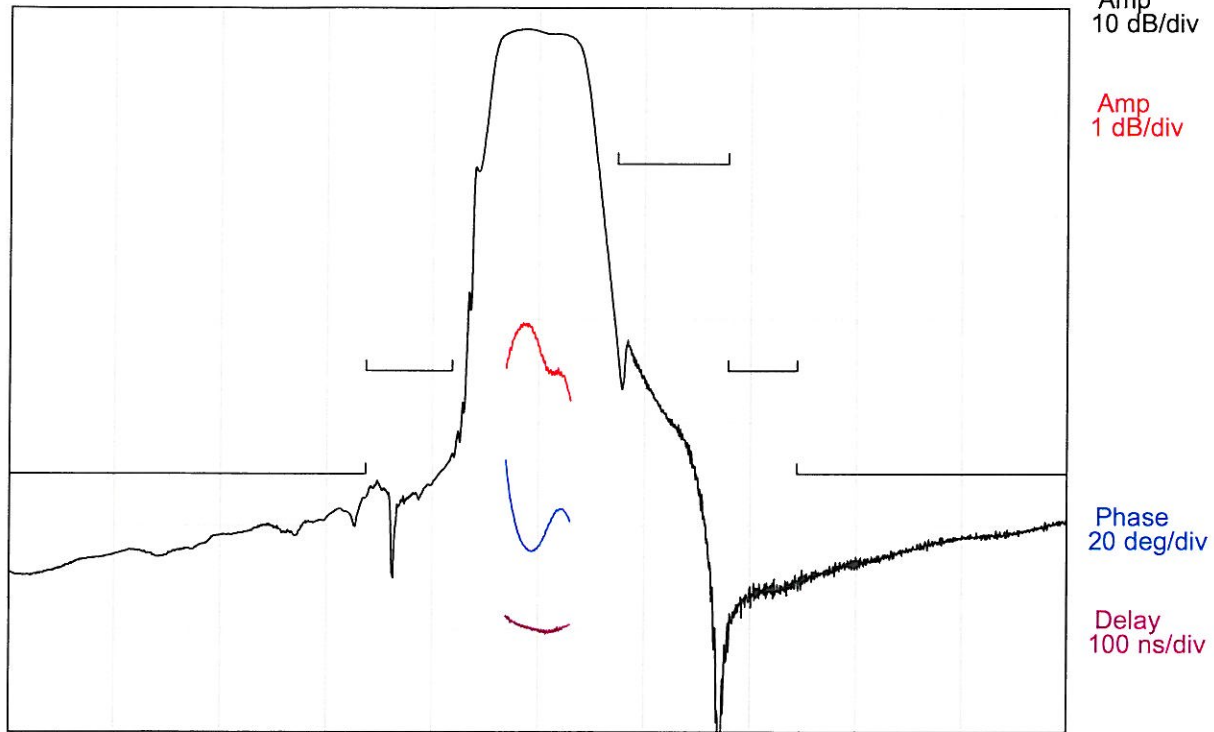


DESCRIPTION

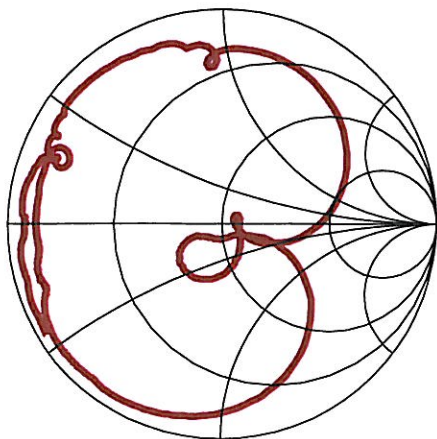
- 915 MHz SAW filter with 26 MHz bandwidth.
- 3.8 x 3.8 mm ceramic LCC package with 6 pads.
- RoHS compliant.

TYPICAL PERFORMANCE

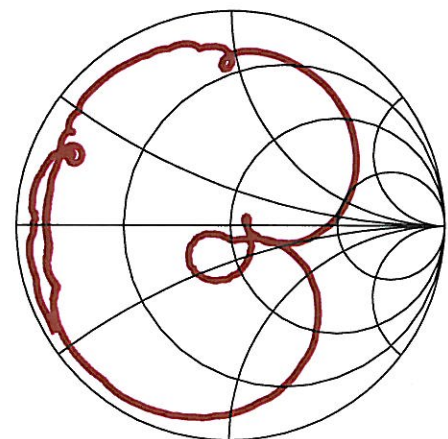


Center = 915 MHz, 43 MHz/div (268.8 kHz incr)

S11 (700-1130 MHz)



S22 (700-1130 MHz)



SPECIFICATION

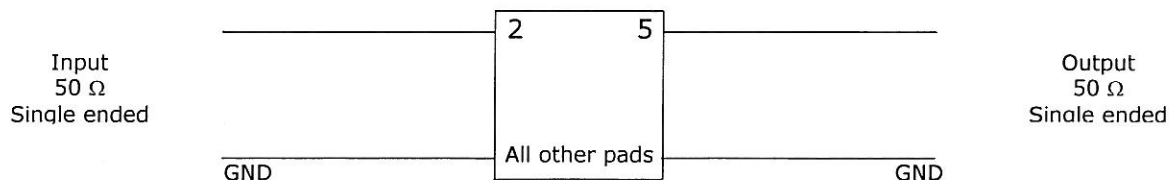
Parameter	Min	Typ	Max	Units
Center Frequency (Fc) ¹	-	915	-	MHz
Passband Width	-13	-	+13	MHz
Insertion Loss (902 to 928 MHz)	-	2.8	3.3	dB
Amplitude Ripple (902 to 928 MHz)	-	1.1	1.5	dB p-p
Relative Attenuation (10 to 700 MHz) ²	50	55	-	dB
Relative Attenuation (700 to 845 MHz) ²	45	50	-	dB
Relative Attenuation (845 to 880 MHz) ²	35	40	-	dB
Relative Attenuation (947 to 992 MHz) ²	15	20	-	dB
Relative Attenuation (992 to 1020 MHz) ²	35	40	-	dB
Relative Attenuation (1020 to 1200 MHz) ²	45	50	-	dB
Temperature Coefficient of Frequency	-32			ppm/°C
Terminating Impedance	50 Ω // 0 nF			
Ambient Temperature	25			°C

- Notes: 1. Fixed reference point.
2. Reference level from 0 dB absolute.

MAXIMUM RATINGS

Parameter	Min	Max	Units
Storage Temperature Range	-40	85	°C
Operating Temperature Range	0	70	°C
Input Power Level	-	10	dBm
DC Voltage	-	10	Volts

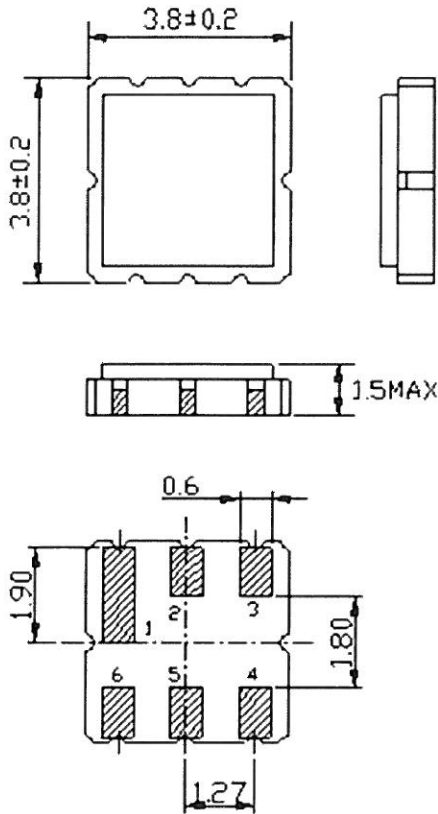
MATCHING CIRCUIT



Notes:

- External matching components are not required.
- Device is intended to operate in a 50 Ω single ended system.

PACKAGE OUTLINE



Units: mm

Typical tolerances are ± 0.15 mm except where indicated.

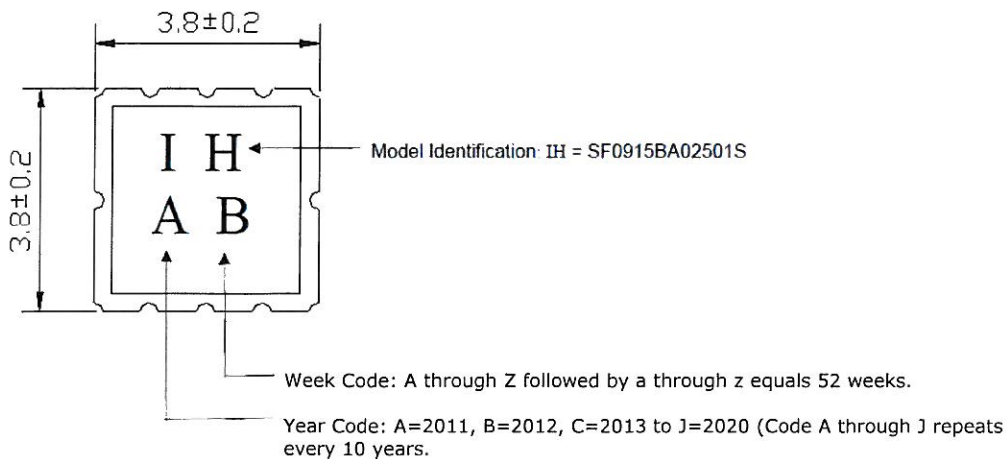
Pad Configuration:

Input: 2
Output: 5
Ground: All other pads

Package Material:

Body: Al_2O_3 ceramic
Lid: Kovar, Ni plated
Terminations: Au plating 1 μ m min, over a 1.3-8.9 μ m Ni plating

MARKING



All specifications are believed to be accurate and reliable. However, Spectrum Microwave reserves the right to make changes without notice.
© 2011 All rights reserved.

	Qty	Qty
1500-1	30	35
Assembly	10-Mar	14-Mar
Wire bond	16-Mar	18-Mar
Open Test	17-Mar	21-Mar
Precap	18-Mar	22-Mar
Seal	22-Mar	24-Mar
Env	25-Mar	28-Mar
BI	30-Mar	4-Apr
Final Test	1-Apr	6-Apr
Finishing	6-Apr	11-Apr
Final visual	7-Apr	12-Apr
Ship	8-Apr	13-Apr

	Qty	Qty
2002	25	25
Assembly	1-Mar	3-Mar
Wire bond	7-Mar	9-Mar
Open Test	8-Mar	10-Mar
Precap	9-Mar	11-Mar
Seal	11-Mar	15-Mar
Env	16-Mar	18-Mar
BI	23-Mar	25-Mar
Final Test	24-Mar	28-Mar
Finishing	30-Mar	1-Apr
Final visual	31-Mar	4-Apr
Ship	1-Apr	5-Apr

	Qty	Qty	Qty
2003	10	35	40
Assembly	1-Mar	2-Mar	23-Mar
Wire bond	4-Mar	7-Mar	28-Mar
Open Test	7-Mar	8-Mar	29-Mar
Precap	8-Mar	9-Mar	30-Mar
Seal	10-Mar	11-Mar	1-Apr
Env	11-Mar	14-Mar	4-Apr
BI	17-Mar	21-Mar	11-Apr
Final Test	21-Mar	23-Mar	13-Apr
Finishing	24-Mar	28-Mar	18-Apr
Final visual	25-Mar	29-Mar	19-Apr
Ship	25-Mar	30-Mar	20-Apr